CMHD3595

SURFACE MOUNT
LOW LEAKAGE
SILICON DIODE



SOD-123 CASE

Central Semiconductor Corp.

www.centralsemi.com

DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMHD3595 is a silicon diode, manufactured by the epitaxial planar process, epoxy molded in a surface mount package, designed for high conductance applications requiring low leakage.

MARKING CODE: C95

MAXIMUM RATINGS: (T_A=25°C)	**SYMBOL**		**UNITS**
Peak Repetitive Reverse Voltage	V_{RRM}	150	V
Peak Working Reverse Voltage	V_{RWM}	125	V
Average Forward Current	I_O	150	mA
Continuous Forward Current	I_F	225	mA
Recurrent Peak Forward Current	i_f	600	mA
Peak Forward Surge Current, tp=1.0s	I_{FSM}	500	mA
Peak Forward Surge Current, tp=1.0μs	I_{FSM}	4.0	A
Power Dissipation	P_D	400	mW
Operating and Storage Junction Temperature	T_J, T_{stg}	-65 to +150	°C
Thermal Resistance	Θ_{JA}	312.5	°C/W

ELECTRICAL CHARACTERISTICS: (T_A=25°C unless otherwise noted)

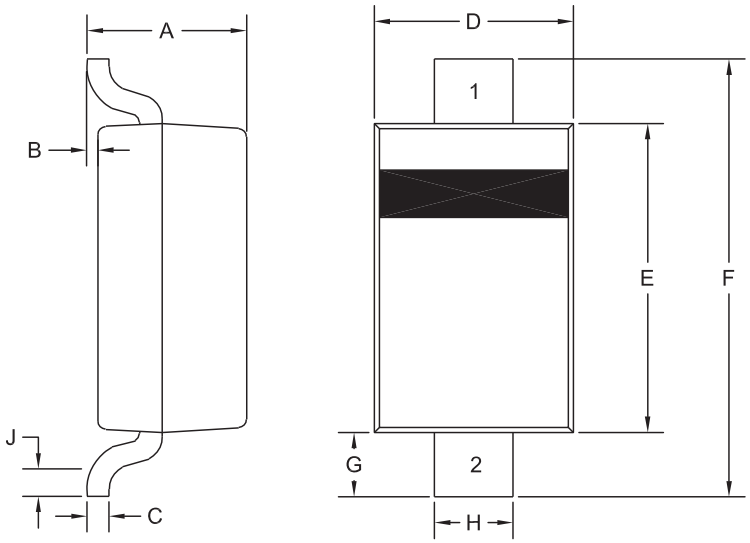
SYMBOL	**TEST CONDITIONS**	**MIN**	**MAX**	**UNITS**
I_R	V_R=125V		1.0	nA
I_R	V_R=125V, T_A=125°C		2.0	μA
I_R	V_R=125V, T_A=150°C		5.0	μA
I_R	V_R=30V, T_A=125°C		300	nA
BV_R	I_R=100μA	150		V
V_F	I_F=1.0mA	0.54	0.69	V
V_F	I_F=5.0mA	0.62	0.77	V
V_F	I_F=10mA	0.65	0.80	V
V_F	I_F=50mA	0.75	0.88	V
V_F	I_F=100mA	0.79	0.92	V
V_F	I_F=200mA	0.83	1.00	V
C_J	V_R=0, f=1.0MHz		8.0	pF
t_{rr}	V_R=3.5V, I_F=10mA, R_L=1.0kΩ		3.0	μs

R6 (17-June 2019)

CMHD3595

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SOD-123 CASE - MECHANICAL OUTLINE



R5

LEAD CODE
1) Cathode
2) Anode

MARKING CODE: C95

DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.037	0.053	0.95	1.35
B	0.000	0.005	0.00	0.12
C	-	0.008	-	0.20
D	0.055	0.071	1.40	1.80
E	0.098	0.110	2.50	2.80
F	0.142	0.154	3.60	3.90
G	0.016	-	0.40	-
H	0.020	0.028	0.50	0.70
J	0.010	-	0.25	-

SOD-123 (REV:R5)

R6 (17-June 2019)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix " TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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